

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 08/25/2022

Details for "OPA353NA/250"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
OPA353NA/250	NIPDAU	Level-2-260C-1 YEAR	Ext-Mfg	DBV 5	2.9x1.6x1.45	18.4

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Precious Metals	Gold	7440-57-5	0.035202	100	1000000	0.191459	1915
Sub-Total			0.035202	100	1000000	0.191459	1915
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.199974	80.00016	800002	1.087633	10876
Thermoplastics	Epoxy	85954-11-6	0.049993	19.99984	199998	0.271906	2719
Sub-Total			0.249967	100	1000000	1.359539	13595
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	6.292686	97.41	974100	34.225122	342251
Copper and Its Alloys	Iron	7439-89-6	0.153748		23800	0.836216	8362
Copper and Its Alloys	Phosphorus	7723-14-0	0.005426	0.083994	840	0.029511	295
Zinc and Its Alloys	Zinc	7440-66-6	0.00814	0.126006	1260	0.044272	443
Sub-Total			6.46	100	1000000	35.135121	351351
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.110339	95.119828	951198	0.60012	6001
Precious Metals	Gold	7440-57-5	0.000905	0.780172	7802	0.004922	49
Precious Metals	Palladium	7440-05-3	0.004756	4.1	41000	0.025867	259
Sub-Total			0.116	100	1000000	0.630909	6309
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	9.445015	85.999997	860000	51.37024	513702
Other Plastics and Rubber	Carbon Black	1333-86-4	0.054913	0.500001	5000	0.298665	2987
Thermoplastics	Epoxy	85954-11-6	1.482648	13.500002	135000	8.063935	80639
Sub-Total			10.982576	100	1000000	59.732839	597328
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.542416	100	1000000	2.950132	29501
Sub-Total			0.542416	100	1000000	2.950132	29501
Total			18.386161			100	1000000

Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality
 For further environmental statements, please go to www.ti.com/ecoinfo
 Created on: 08/25/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.